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Date: February 12, 2003

Sonia V. McVein  
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PATENT  
36856.585

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Keiji INOUE et al.

Serial No.: 09/995,643

Filed: November 29, 2001

Title: MOUNTING STRUCTURE FOR  
MODULE SUBSTRATES

Art Unit: 2827

Examiner: T. Dinh

AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action dated September 12, 2002, the period for response to which has been extended to February 12, 2003, by the accompanying Petition for Two-Month Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1-18 with the following claims:

1. (amended) A module substrate mounting structure comprising:  
a motherboard having connecting pads disposed on a surface thereof; and  
a plurality of module substrates each having connecting members attached to a surface thereof via connecting terminals disposed on each of said plurality of module